

LIST OF REFERENCES CITED
BY APPLICANT
(Use several sheets if necessary)



Patent and Trademark Office

Atty Docket No.: 70408

Ser. No.:

Applicant: SCHREDL et al.

Filing Date:

Group: 1772

U.S. PATENT DOCUMENTS

Ex- aminer Initial	Document No.	Date	Name	Class	Sub- class	Filing Date
<u>U</u>	<u>5,611,884</u>	<u>March 18, 1997</u>	<u>Bearinger et al.</u>			<u>Dec. 11, 1995</u>
<u>U</u>	<u>5,436,503</u>	<u>July 25, 1995</u>	<u>Kunitomo et al.</u>			<u>Nov. 17, 1993</u>
<u>K</u>	<u>5,400,950</u>	<u>March 28, 1995</u>	<u>Myers et al.</u>			<u>Feb. 22, 1994</u>

FOREIGN PATENT DOCUMENTS

Ex- aminer Initial	Document No.	Date	Country	Class	Sub- class	Translation Yes/No
<u>U</u>	<u>DE 41 09 363</u>	<u>Sept. 24, 1992</u>	<u>Germany</u>			<u>No</u>
<u>U</u>	<u>DE 41 38 779</u>	<u>July 29, 1993</u>	<u>Germany</u>			<u>No</u>
<u>U</u>	<u>60067925</u>	<u>April 18, 1985</u>	<u>Japan</u>			<u>Yes</u>

OTHER PRIOR ART (Including Author, Title, Date,
Pertinent Pages, Etc.)

Ex- aminer Initial	Author	Date	Title	Textbook in	Translation Yes/No
<u>U</u>	<u>Roland Heitmann</u>	<u>1995</u>	<u>Die elementaren Verbin-dungen: BGA und Flip-Chip</u>	<u>Productronic 7</u>	<u>No</u>
<u>U</u>		<u>Jan. 1996</u>	<u>Lotkugeln auf Chip und Umhüllung</u>	<u>Elektronik</u>	<u>No</u>

Savage, J.
Examiner

L. Tran

1/21/03
Date Considered